

Notes:

1.0 Orientations

1.1 Wafer surface is normal to X axis  $\pm 0.5^\circ$

1.2 Flats

1.2.1 Primary flat is normal to  $\langle +Z \rangle \pm 0.5^\circ$ .

1.2.2 Secondary flat is  $135^\circ \pm 1^\circ$  clockwise from the primary flat when viewing the  $-X$  face.

3.0 Edge

3.1 All edges rounded with  $R0.27 \pm 0.08\text{mm}$ .

3.2 No chips greater than 0.5mm in penetration and 1.0mm in length.

4.0 Surfaces

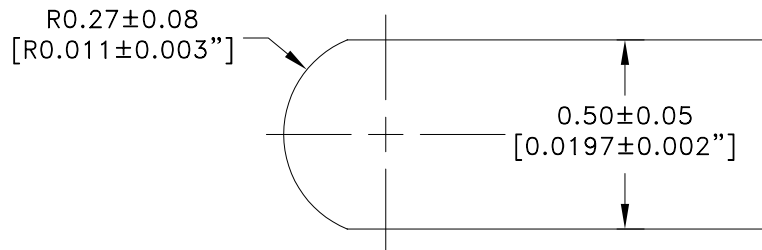
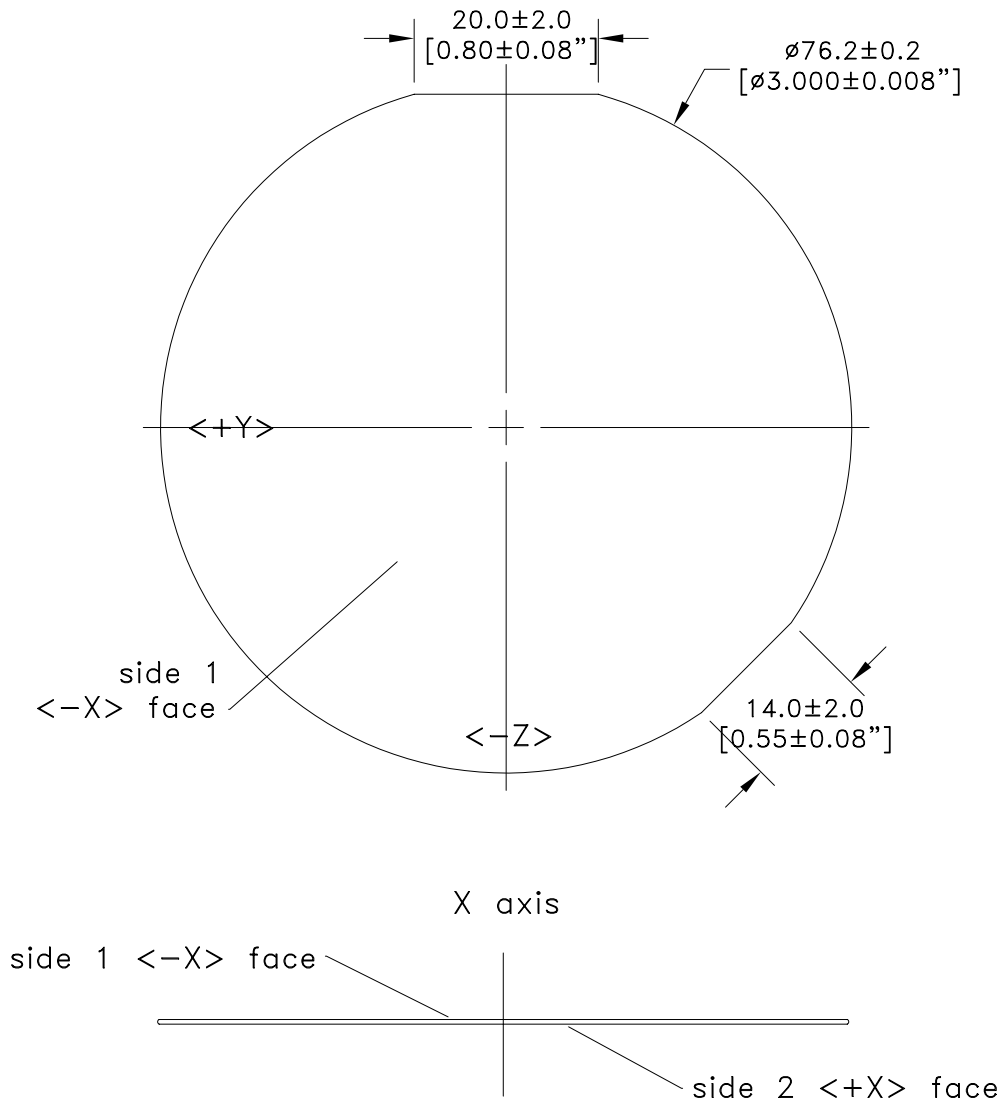
4.1 Side 1  $\langle -X \rangle$  face

Polished 10-5 scratch-dig with 1mm edge exclusion. No pits or scratches visible with reflected light and unaided eye.

4.2 Side 2  $\langle +X \rangle$  face


Ground, Ra 0.50-0.70 $\mu\text{m}$ .

**For Reference Only**



Wafer Edge Detail, 50:1

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Material:	DR.	Igordon	08-25-03	 <b>Crystal Technology, Inc.</b> An EPCOS Company
Lithium Niobate	CHK.			
Unless otherwise specified, dimensions in mm	APPD.			Title:
<b>Tolerances</b>				LNIO 76.2 $\phi$ x 0.5mm, -X Po/Gr, +Z FLT
Inches	Millimeters	Wafer Code:		Size: A
.X $\pm$ 0.1	X $\pm$ 0.5	LNA--X:076.050CN		Dwg. No: 97-01183-01
.XX $\pm$ 0.01	.X $\pm$ 0.25	Customer Approval:		Rev: D
.XXX $\pm$ 0.005	.XX $\pm$ 0.1			Scale: 1.2:1
.XXXX $\pm$ 0.0020	.XXX $\pm$ 0.05			Sheet 1 of 1
Angles $\pm$ 0.5°		DO NOT SCALE DRAWING		